



# TSML3710

Vishay Semiconductors

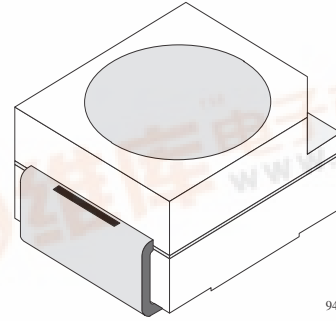
## GaAs/GaAlAs Infrared Emitting Diode in SMT Package

### Description

TSML3710 is an infrared emitting diode in GaAlAs on GaAs technology in miniature PLCC2 SMD package.

### Features

- SMT IRED with extra high radiant power
- Low forward voltage
- Compatible with automatic placement equipment
- EIA and ICE standard package
- Suitable for infrared, vapor phase and wavesolder process
- Packed in 8 mm tape
- Suitable for pulse current operation
- Extra wide angle of half intensity  $\varphi = \pm 60^\circ$
- Peak wavelength  $\lambda_p = 950 \text{ nm}$
- Matched with TEMT3700 phototransistor



94 8553

### Applications

- IR emitter in photointerrupters, transmissive sensors and reflective sensors
- Household appliance
- IR emitter in low space applications
- Tactile keyboards

### Parts Table

Part	Ordering code	Remarks
TSML3710	TSML3710-GS08	MOQ 7500pcs (1500 pcs per reel)

### Absolute Maximum Ratings

$T_{amb} = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Test condition	Symbol	Value	Unit
Reverse Voltage		$V_R$	5	V
Forward Current		$I_F$	100	mA
Peak Forward Current	$t_p/T = 0.5, t_p = 100 \mu\text{s}$	$I_{FM}$	200	mA
Surge Forward Current	$t_p = 100 \mu\text{s}$	$I_{FSM}$	1	A
Power Dissipation		$P_V$	170	mW
Junction Temperature		$T_j$	100	$^\circ\text{C}$
Operating Temperature Range		$T_{amb}$	- 40 to + 85	$^\circ\text{C}$
Storage Temperature Range		$T_{stg}$	- 40 to +100	$^\circ\text{C}$
Soldering Temperature	$t \leq 10\text{sec}$	$T_{sd}$	260	$^\circ\text{C}$
Thermal Resistance Junction/Ambient		$R_{thJA}$	450	K/W



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## Basic Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Forward Voltage	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$V_F$		1.35	1.7	V
	$I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$	$V_F$		2.6	3.2	V
Temp. Coefficient of $V_F$	$I_F = 1\text{ mA}$	$TK_{V_F}$		-1.85		mV/K
Reverse Current	$V_R = 5\text{ V}$	$I_R$			100	$\mu\text{A}$
Junction Capacitance	$V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$	$C_j$		25		pF
Radiant Intensity	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$I_e$	4	8		mW/sr
	$I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$	$I_e$		60		mW/sr
Radiant Power	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$\phi_e$		35		mW
Temp. Coefficient of $\phi_e$	$I_F = 100\text{ mA}$	$TK_{\phi_e}$		-0.6		%/K
Angle of Half Intensity		$\varphi$		$\pm 60$		deg
Peak Wavelength	$I_F = 100\text{ mA}$	$\lambda_p$		950		nm
Spectral Bandwidth	$I_F = 100\text{ mA}$	$\Delta\lambda$		50		nm
Temp. Coefficient of $\lambda_p$	$I_F = 100\text{ mA}$	$TK_{\lambda_p}$		0.2		nm/K
Rise Time	$I_F = 20\text{ mA}$	$t_r$		800		ns
	$I_F = 1\text{ A}$	$t_r$		500		ns
Fall Time	$I_F = 20\text{ mA}$	$t_f$		800		ns
	$I_F = 1\text{ A}$	$t_f$		500		ns

## Typical Characteristics ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

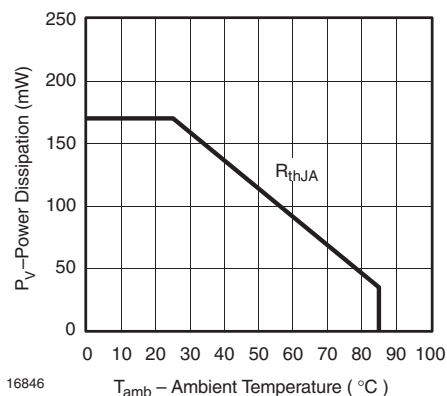


Figure 1. Power Dissipation vs. Ambient Temperature

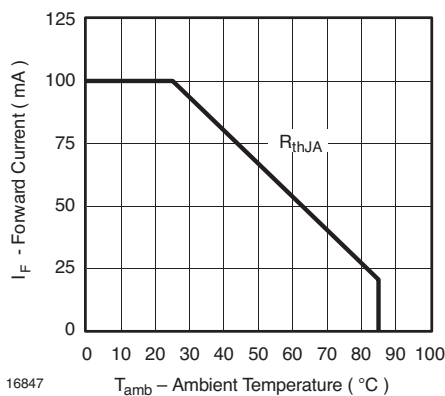


Figure 2. Forward Current vs. Ambient Temperature

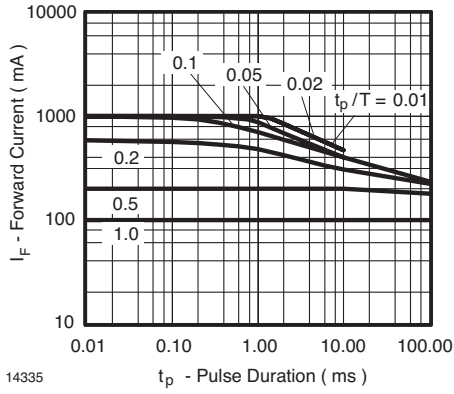


Figure 3. Pulse Forward Current vs. Pulse Duration

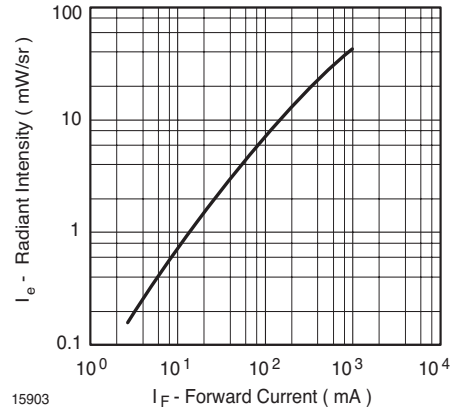


Figure 6. Radiant Intensity vs. Forward Current

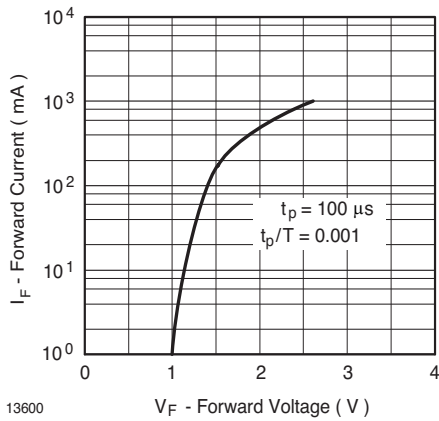


Figure 4. Forward Current vs. Forward Voltage

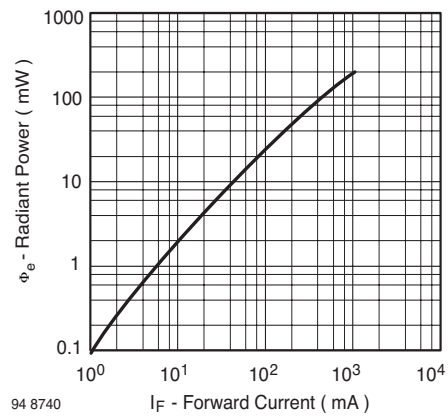


Figure 7. Radiant Power vs. Forward Current

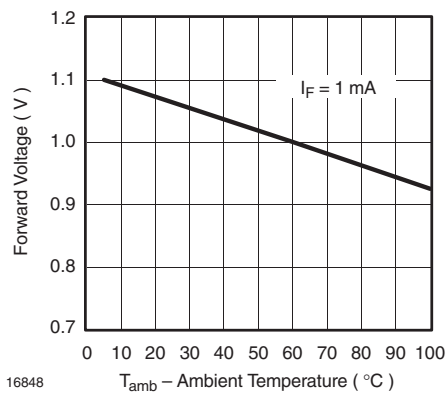


Figure 5. Forward Voltage vs. Ambient Temperature

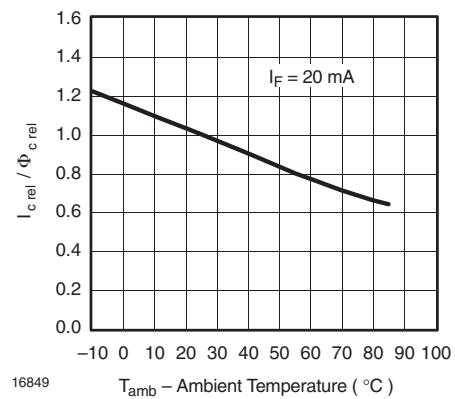


Figure 8. Rel. Radiant Intensity/Power vs. Ambient Temperature

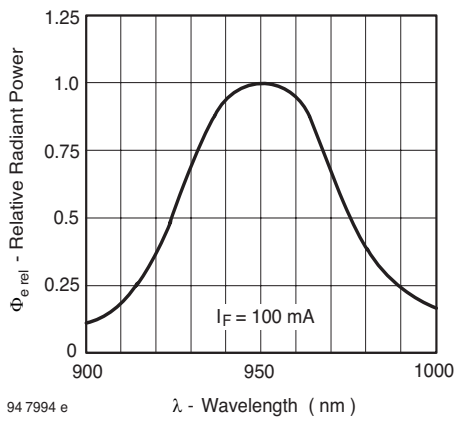


Figure 9. Relative Radiant Power vs. Wavelength

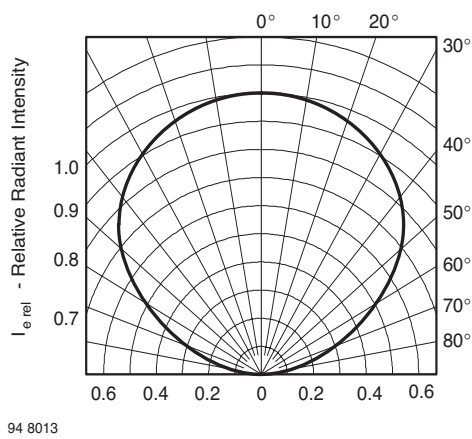
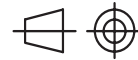
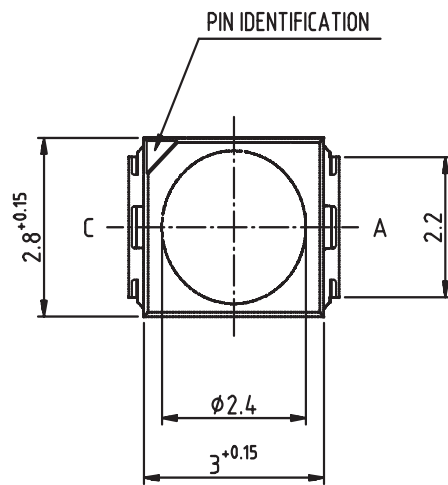
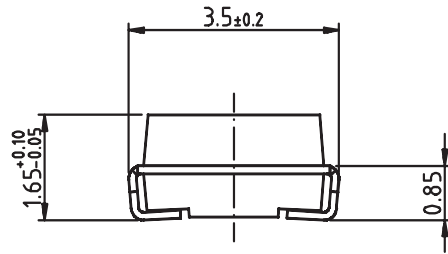


Figure 10. Relative Radiant Intensity vs. Angular Displacement



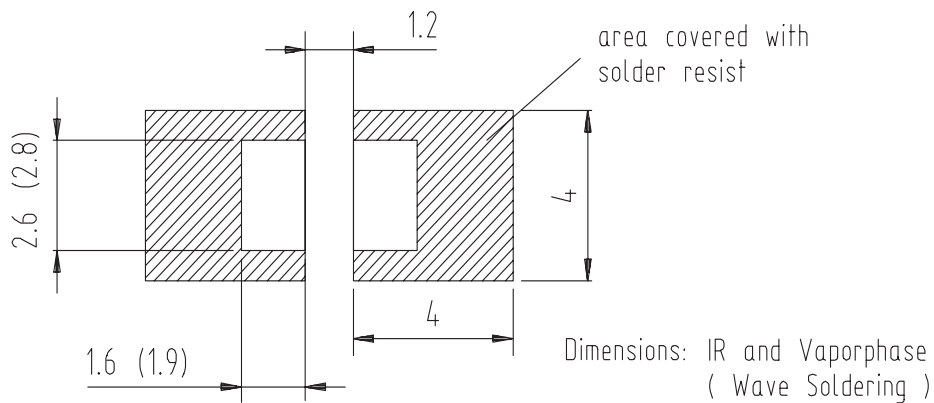
## Package Dimensions in mm



Technical drawings  
according to DIN  
specifications

95 11314

## Pad Layout



95 10966

## Temperature - Time Profile

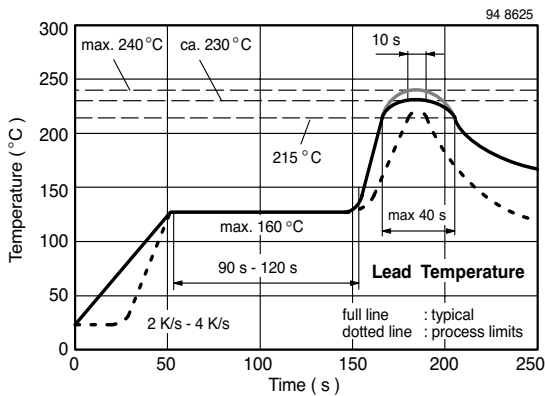


Figure 11. Infrared Reflow Soldering Optodevices (SMD Package)

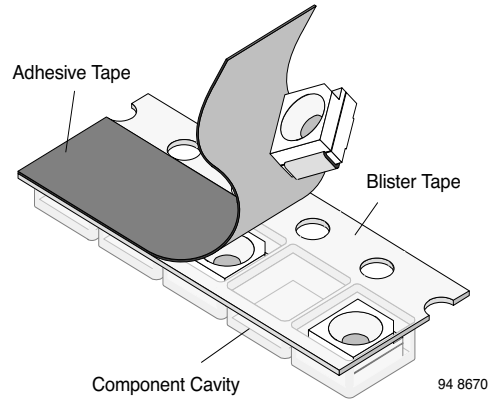


Figure 12. Blister Tape

## Drypack

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## Floor Life

Floor life (time between soldering and removing from MBB) must not exceed the time indicated in J-STD-020.

TSML 3710 is released for:

Moisture Sensitivity Level 2, according to JEDEC, J-STD-020

Floor Life: 1 year

Conditions:  $T_{amb} < 30^{\circ}\text{C}$ ,  $\text{RH} < 60\%$

## Drying

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or Label.

Devices taped on reel dry using recommended conditions 192 h @  $40^{\circ}\text{C}$  (+  $5^{\circ}\text{C}$ ),  $\text{RH} < 5\%$

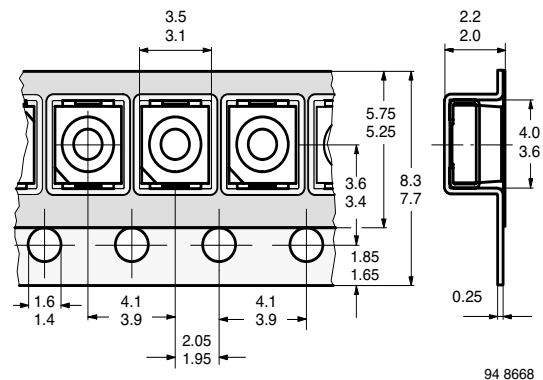


Figure 13. Tape Dimensions in mm for PLCC-2

## Missing Devices

A maximum of 0.5% of the total number of components per reel may be missing, exclusively missing components at the beginning and at the end of the reel. A maximum of three consecutive components may be missing, provided this gap is followed by six consecutive components.

## Cover Tape Removal Force

The removal force lies between 0.1 N and 1.0 N at a removal speed of 5 mm/s.

In order to prevent components from popping out of the blisters, the cover tape must be pulled off at an angle of 180° with regard to the feed direction.

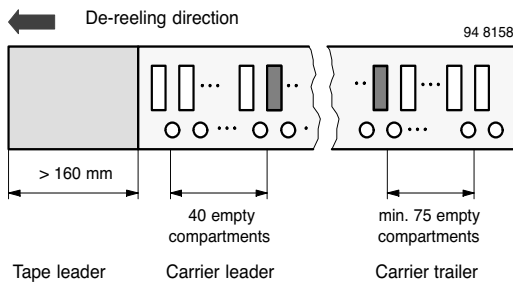


Figure 14. Beginning and End of Reel

The tape leader is at least 160 mm and is followed by a carrier tape leader with at least 40 empty compartments. The tape leader may include the carrier tape as long as the cover tape is not connected to the carrier tape.

The least component is followed by a carrier tape trailer with a least 75 empty compartments and sealed with cover tape.

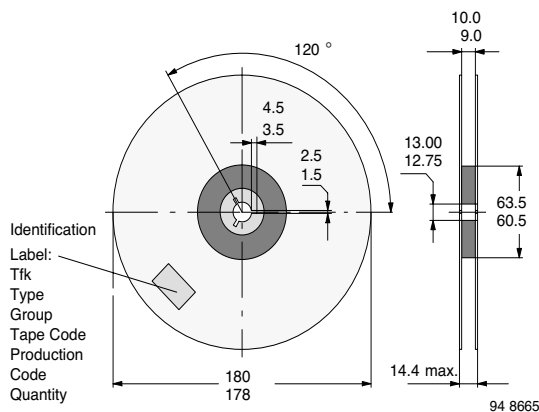


Figure 15. Dimensions of Reel

### Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**Vishay Semiconductor GmbH** has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**Vishay Semiconductor GmbH** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

**We reserve the right to make changes to improve technical design  
and may do so without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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